

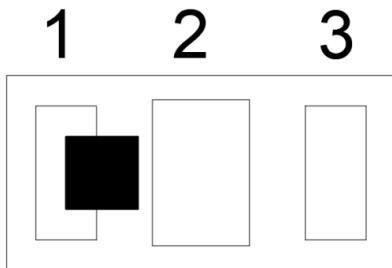
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

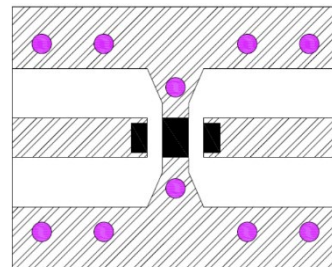
NO.	Parameter	Frequency (MHz)	Min.	Max.
1	Insertion Loss (dB)	3300~7250		0.80
2	Return Loss(dB)	3300~7250		10
3	Attenuation (dB)	450~960	25	
		1427~1710	20	
		1710~1910	20	
		1910~2200	20	
		2300~2400	20	
		2400~2500	20	
		2500~2690	20	
4	In/Output Impedance (Ω)	50		

Construction



PIN	Connection
P1	Input port
P2	GND
P3	Output port

Mounting Considerations

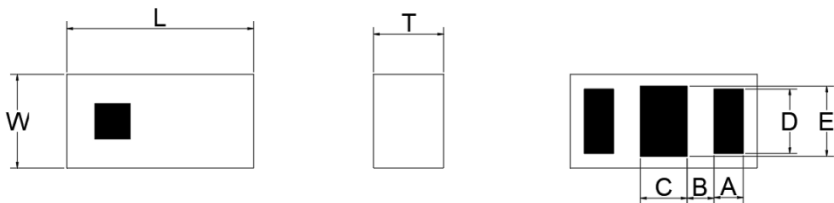


- Land
- ▨ Solder
- Through-hole

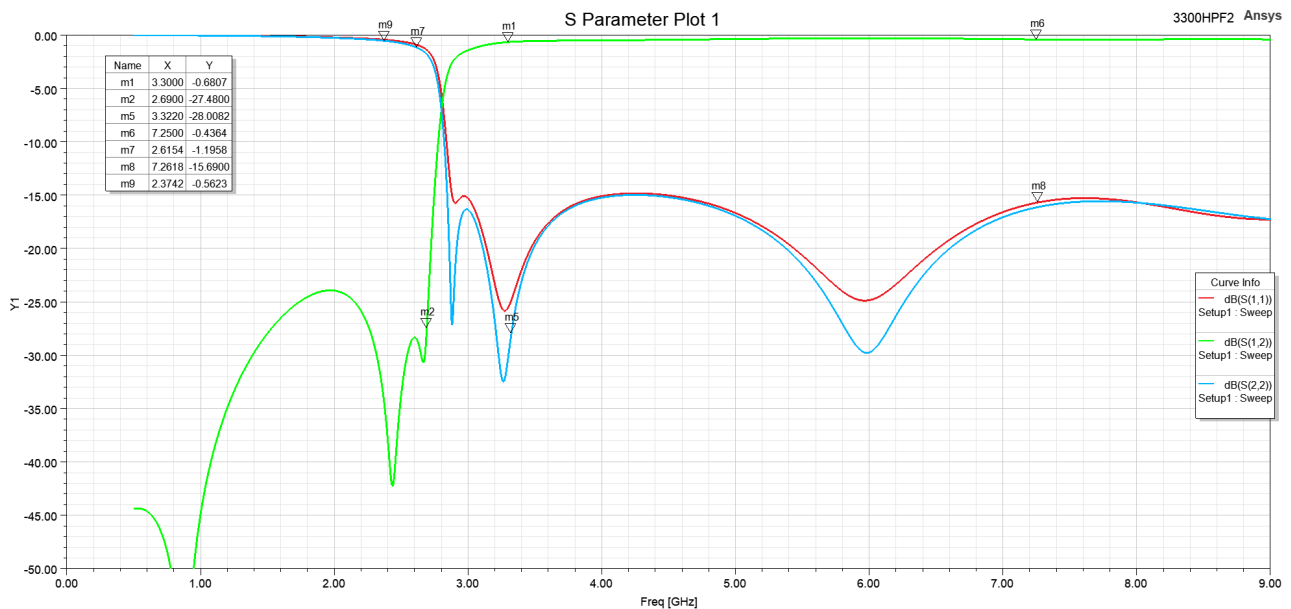
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

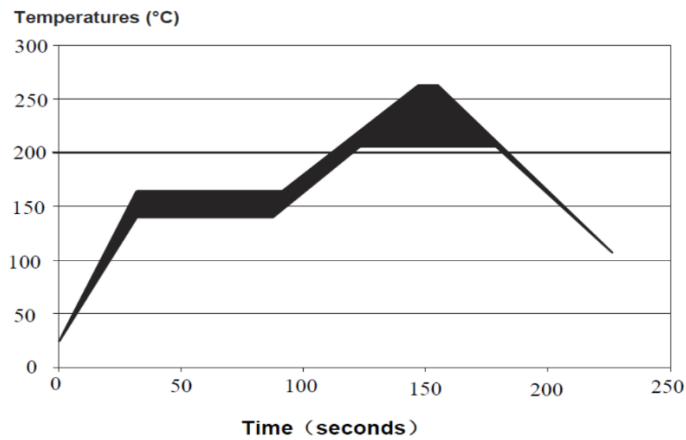
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60±0.10
	W	0.80±0.10
	T	0.65MAX
	A	0.25±0.10
	B	0.23±0.10
	C	0.40±0.10
	D	0.55±0.10
	E	0.60±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.